

Title (en)
ELECTRONIC PART MANUFACTURING METHOD

Title (de)
VERFAHREN ZUR HERSTELLUNG ELEKTRONISCHER BAUTEILE

Title (fr)
PROCÉDÉ DE FABRICATION DE COMPOSANT ÉLECTRONIQUE

Publication
EP 2451255 A1 20120509 (EN)

Application
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Abstract (en)
The present invention provides a new method for manufacturing an electronic part, which is capable of reducing the number of steps of superpose-printing, achieving positional accuracy (alignment accuracy) of precise superposed patterns, and layering with substantially no difference in level, thereby improving productivity and dimensional accuracy and eliminating defects. The method for manufacturing an electronic part includes the steps of forming a composite ink pattern layer on a releasing surface of a transfer plate using a relief offset method, and then simultaneously reversely transferring the composite ink pattern layer to a printing object. Various organic transistor elements are formed by combining a conductive ink, an insulating ink, and an ink containing a semiconductor.

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